



Material Content Data Sheet



Sales Product Name		IPS60R3K4CE		Issued		19. July 2018		
MA#		MA001581478						
Package		PG-TO251-3-343		Weight*		339.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.000	0.29	0.29	2946	2946
leadframe	non noble metal	iron	7439-89-6	0.160	0.05		472	
	inorganic material	phosphorus	7723-14-0	0.048	0.01		141	
	non noble metal	copper	7440-50-8	159.794	47.11	47.17	470998	471611
wire	non noble metal	aluminium	7429-90-5	4.325	1.27	1.27	12748	12748
encapsulation	organic material	carbon black	1333-86-4	0.714	0.21		2105	
	plastics	epoxy resin	-	19.285	5.68		56843	
	inorganic material	silicondioxide	60676-86-0	122.852	36.21	42.10	362109	421057
leadfinish	non noble metal	tin	7440-31-5	4.771	1.41	1.41	14062	14062
solder	noble metal	silver	7440-22-4	0.035	0.01		104	
	non noble metal	tin	7440-31-5	0.028	0.01		83	
	non noble metal	lead	7439-92-1	1.349	0.40	0.42	3977	4164
heatspreader	non noble metal	iron	7439-89-6	0.025	0.01		73	
	inorganic material	phosphorus	7723-14-0	0.007	0.00		22	
	non noble metal	copper	7440-50-8	24.874	7.33	7.34	73317	73412
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com